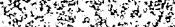


783	Subclass	I.P.E.				PATENT NUMBER
361	Class					
U.S. UTILITY Patent Application						
AK [Signature] SCANNED			Q.A. [Signature]			PATENT DATE
APPLICATION NO. 09/684519	CONT/PRIOR	CLASS 361	SUBCLASS 783	ART. UNIT 2841	EXAMINER H. Bui	
APPLICANTS Yin-Yuan Lee						
TITLE Thermally compliant PCB substrate for the application of chip scale PACKAGES						
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ISSUING CLASSIFICATION

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TERMINAL DISCLAIMER		DRAWINGS		CLAIMS ALLOWED	
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.		Sheets Drwg. 3	Figs. Drwg. 8	Print Fig. Sc	Total Claims 54
		 (Primary Examiner) H. H. H. (Date) 7/15/03		NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____.				ISSUE FEE	
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